## AMENDMENTS TO THE CLAIMS

Docket No.: 80079(302721)

The following listing of claims will replace all prior listings, and versions, of the claims.

1. (Currently Amended): A metal-coated resin molded article comprising a substrate made of a resin composition and a metal layer formed on said substrate, wherein said resin composition comprises a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer, said epoxy-group containing ethylene copolymer contains 50 to 99.9 wt% of an ethylene unit and 0.1 to 30 wt% of at least one of an unsaturated carboxylic acid glycidyl ester unit and an unsaturated glycidyl ether unit in the molecule thereof, and a content of said epoxy-group containing ethylene copolymer is in a range of 0.1 to 25 parts by weight with respect to 100 parts by weight of said liquid-crystalline polyester; and wherein said metal layer is formed by physical vapor deposition of a metal onto said substrate and said substrate is treated with plasma prior to formation of said metal layer;

and wherein said liquid-crystalline polyester is the reaction product obtained by performing the ester-exchange and polycondensation reaction in the presence of an imidazole compound represented by the following chemical formula:

wherein, each of " $R_1$ " to " $R_4$ " is selected from hydrogen atom, alkyl group having a carbon number of 1 to 4, hydroxymethyl group, cyano group, cyanoalkyl group having a carbon number of 1 to 4, cyanoalkoxy group having a carbon number of 1 to 4, carboxyl group, amino group, aminoalkyl group having a carbon number of 1 to 4, aminoalkoxy group having a carbon number of 1 to 4, phenyl group, benzyl group, phenylpropyl group, and a formyl group.

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2. (Original) The metal-coated resin molded article as set forth in claim 1, wherein said liquid-crystalline polyester is a reaction product obtained by an ester-exchange and polycondensation reaction of at least one of an aromatic dicarboxylic acid and an aromatic hydroxycarboxylic acid with an acylated compound obtained by acylating a phenolic hydroxyl group of at least one of an aromatic diol and an aromatic hydroxycarboxylic acid with a fatty acid anhydride.

## 3. (Canceled)

- 4. (Original) The metal-coated resin molded article as set forth in claim 1, wherein said epoxy-group containing ethylene copolymer contains 80 to 95 wt% of the ethylene unit and 5 to 15 wt% of at least one of the unsaturated carboxylic acid glycidyl ester unit and the unsaturated glycidyl ether unit in the molecule thereof.
- 5. (Original) The metal-coated resin molded article as set forth in claim 1, wherein said resin composition contains a fiber-like inorganic filler having a diameter of 6 to 15  $\mu$ m and an aspect ratio of 5 to 50.
- (Original) The metal-coated resin molded article as set forth in claim 1, wherein said resin composition contains 20 to 235 parts by weight of a whisker with respect to 100 parts by weight of said liquid-crystalline polyester.
- (Original) The metal-coated resin molded article as set forth in claim 1, wherein said resin composition contains 10 to 40 parts by weight of a plate-like inorganic filler with respect to 100 parts by weight of said liquid-crystalline polyester.

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8. (Previously Presented) The metal-coated resin molded article as set forth in claim 1, wherein said metal layer consists essentially of a metal material selected from the group consisting of copper, nickel, gold, aluminum, titanium, molybdenum, chromium, tungsten, tin, lead, brass, Nichrome and an alloy thereof.

 (Original) The metal-coated resin molded article as set forth in claim 1, wherein said metal layer is formed in a circuit pattern.

 (Previously Presented) A method of producing a metal-coated resin molded article comprising the steps of

molding a resin composition to obtain a substrate;

treating said substrate with plasma; and

forming a metal layer on a surface of said substrate by physical vapor deposition of a metal onto said plasma-treated substrate,

wherein said resin composition comprises a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer, said epoxy-group containing ethylene copolymer contains 50 to 99.9 wt% of an ethylene unit and 0.1 to 30 wt% of at least one of an unsaturated carboxylic acid glycidyl ester unit and an unsaturated glycidyl ether unit in the molecule thereof, and a content of said epoxy-group containing ethylene copolymer is in a range of 0.1 to 25 parts by weight with respect to 100 parts by weight of said liquid-crystalline polyester.

- 11. (Canceled)
- 12. (Canceled)

13. (Original) The method as set forth in claim 10 comprising the step of performing a heat treatment to said substrate at a temperature between a lower limit temperature calculated by subtracting 120°C from a flow-beginning temperature of said liquid-crystalline polyester, and an upper limit temperature calculated by subtracting 20°C from the flow-beginning temperature.

- 14. (Original) The method as set forth in Claim 10, wherein said liquid-crystalline polyester is prepared by an ester-exchange and polycondensation reaction of at least one of an aromatic dicarboxylic acid and an aromatic hydroxycarboxylic acid, with an acylated compound obtained by acylating a phenolic hydroxyl group of at least one of an aromatic diol and an aromatic hydroxycarboxylic acid with a fatty acid anhydride.
- 15. (Original) The method as set forth in Claim 14, wherein the ester-exchange and polycondensation reaction is performed in the presence of an imidazole compound represented by the following chemical formula:

wherein, each of "R<sub>1</sub>" to "R<sub>4</sub>" is selected from hydrogen atom, alkyl group having a carbon number of 1 to 4, hydroxymethyl group, cyano group, cyanoalkyl group having a carbon number of 1 to 4, cyanoalkoxy group having a carbon number of 1 to 4, carboxyl group, amino group, aminoalkyl group having a carbon number of 1 to 4, aminoalkoxy group having a carbon number of 1 to 4, phenyl group, benzyl group, phenylpropyl group, and a formyl group.  (Original) The method as set forth in Claim 10 comprising the step of forming a circuit pattern in said metal layer by laser patterning.